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•	Members of the Texas Instruments Widebus™ Family	SN74ABTE1624		. WD PACKAGE GG OR DL PACKAGE IEW)
•	Support the VME64 ETL Specification			-
•	Reduced, TTL-Compatible, Input Threshold	1DIR		48 V _{CC} BIAS
	Range	1B1 [47 1A1
٠	High-Drive Outputs (I _{OH} = –60 mA,	2B1	3	46 2A1
	I_{OL} = 90 mA) Support 25- Ω Incident-Wave	GND	4	45 GND
	Switching	1B2		44 1A2
•	V _{CC} BIAS Pin Minimizes Signal Distortion	2B2	6	43 2A2
	During Live Insertion	V _{CC}	7	42 V _{CC}
•	Internal Pullup Resistor on OE Keeps	1B3		41 A3
•	Outputs in High-Impedance State During	2B3	9	40 2A3
	Power Up or Power Down	GND		39 GND
•	-	1B4 L		38 AA4
•	Distributed V _{CC} and GND Pins Minimize	2B4 [37 2A4
	High-Speed Switching Noise	1B5 [13	36 A 1A5
•	Equivalent 25- Ω Series Damping Resistor	2B5	14	35 2A5
	on B Port	GND		34 GND
٠	Bus Hold on Data Inputs Eliminates the	1B6 [33 A6
	Need for External Pullup/Pulldown	2B6 🛛	17	32 2A6
	Resistors	V _{CC}	18	31 V _{CC}
		1B7 🛛	19	30 🛛 1A7
desc	ription	2B7 [20	29 2A7
	The 'APTE16245 devices are 16 bit (duel estal)	GND 🛛	21	28 GND
	The 'ABTE16245 devices are 16-bit (dual-octal)	1B8 [22	27] 1A8
	noninverting 3-state transceivers designed for synchronous two-way communication between	2B8 [23	26 2A8
	data buses. The control-function implementation	2DIR [24	25 OE
	minimizes external timing requirements. These			1

one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated. When \overline{OE} is low, the device is active.

The B port has an equivalent $25 \cdot \Omega$ series output resistor to reduce ringing. Active bus-hold inputs also are on the B port to hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via $V_{CC}BIAS$, which establishes a voltage between 1.3 V and 1.7 V when V_{CC} is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

devices can be used as two 8-bit transceivers or

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2001, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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TA	PACKA	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING						
	SSOP – DL	Tube	SN74ABTE16245DL	ABTE16245						
–40°C to 85°C	330F - DL	Tape and reel	SN74ABTE16245DLR	ABTE 10243						
	TSSOP – DGG	Tape and reel	SN74ABTE16245DGGR	ABTE16245						
–55°C to 125°C	CFP – WD	Tube	SNJ54ABTE16245WD	SNJ54ABTE16245WD						

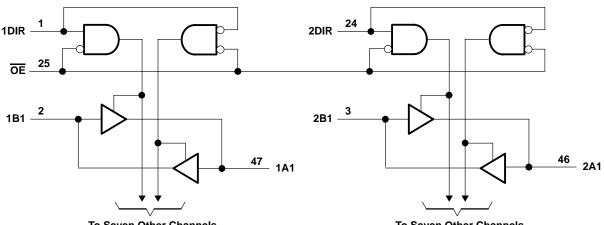
ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

> FUNCTION TABLE (each 8-bit section)

INP	UTS	
OE	DIR	OPERATION
L	L	A data to B bus
L	Н	B data to A bus
н	Х	Isolation

logic diagram (positive logic)



To Seven Other Channels

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC} and V _{CC} BIAS	
Input voltage range, V _I (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high state or power-off state, V_O 0.5 V to	
Current into any output in the low state, I _O 12	8 mA
Input clamp current, I _{IK} (V _I < 0)1	8 mA
Output clamp current, I _{OK} (V _O < 0)5	0 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	°C/W
DL package	
Storage temperature range, T _{stg} –65°C to 1	50°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			SN54ABTE16245			SN74	ABTE16	6245		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} , V _{CC} BIAS	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
	High lovel input voltage	OE	2			2			v	
VIH	High-level input voltage	Except OE	1.6			1.6				
\/		OE			0.8			0.8	v	
VIL	Low-level input voltage	Except OE			1.4			1.4		
VI	Input voltage		0		VCC	0		VCC	V	
lou	High lovel output ourrept	B bus			-12			-12	mA	
ЮН	High-level output current	A bus			-24			-60	ША	
le:		B bus			12			12	mA	
IOL	Low-level output current	A bus			64			90	mA	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10			10	ns/V	
T _A	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA		TERTO	NDITIONS	SN	54ABTE1	6245	SN	74ABTE1	6245	
PAI	RAMETER	IESI CC	ONDITIONS	MIN	түр†	MAX	MIN	түр†	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lı = –18 mA			-1.2			-1.2	V
		V _{CC} = 5.5 V,	I _{OH} = −100 μA			V _{CC} -0.2			V _{CC} -0.2	
	B port		I _{OH} = -1 mA	2.4			2.4			
Val		V _{CC} = 4.5 V	I _{OH} = -12 mA	2			2			v
VOH		V _{CC} = 5.5 V,	I _{OH} = -1 mA			4.5			4.5	v
	A port	V _{CC} = 4.5 V	I _{OH} = -32 mA	2.4			2.4			
		VCC = 4.5 V	I _{OH} = -64 mA				2			
	Dinort		I _{OL} = 1 mA			0.4			0.4	
Va	B port	V _{CC} = 4.5 V	I _{OL} = 12 mA						0.8	v
VOL	A port	V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55			0.55	v
	A port	VCC = 4.5 V	I _{OL} = 90 mA						0.9	
			V _I = 0.8 V	100			100			
l(hold)	B port	V _{CC} = 4.5 V	V _I = 2 V	-100			-100			μA
		V _{CC} = 5.5 V,	V _I = 0 to 5.5 V			±500			±500	
1.	Control inputs	V _{CC} = 5.5 V,	VI = VCC or GND			±1			±1	
łı	A or B ports	VCC = 5.5 V,	VI = VCC OLGND			±20			±20	μA
^I OZH [‡]	A port	V _{CC} = 5.5 V,	V _O = 2.7 V			10			10	μA
Iozl‡	A port	V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-10			-10	μA
1.	A port			-50	-120	-180	-50		-180	
10	B port	V _{CC} = 5.5 V,	V _O = 2.5 V	-25	-52	-90	-25		-90	mA
loff		V_{CC} = 0, V_{I} or V_{O} \leq	4.5 V, V _{CC} BIAS = 0			±100			±100	μA
			Outputs high		28	36		28	36	
ICC	A or B ports	$V_{CC} = 5.5 \text{ V}, I_O = 0,$ $V_I = V_{CC} \text{ or GND}$	Outputs low		38	48		38	48	mA
			Outputs disabled		20	32		20	32	
1000	A or P porto	V _{CC} = 5 V,	OE high		0.02			0.02		mA/
ICCD	A or B ports	C _L = 50 pF	OE low		0.33			0.33		MHz
Ci	Control inputs	V _I = 2.5 V or 0.5 V	V _I = 2.5 V or 0.5 V			10		2.5	4	pF
Cio	I/O ports	V _O = 2.5 V or 0.5 V				13		4.5	8	pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The parameters IOZH and IOZL include the input leakage current.



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live-insertion specifications over recommended operating free-air temperature range

	METER		SN5	SN54ABTE16245			SN74ABTE16245				
			MIN	TYP†	MAX	MIN	түр†	MAX	UNIT		
	$V_{CC} = 0 \text{ to } 4.5 \text{ V}, V_{CC} \text{BIAS} = 4.5 \text{ V to } 5.5 \text{ V},$ $I_{O(DC)} = 0$					250	700		250	700	μA
	ССЫАЗ)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}^{\ddagger}, V_{CC}\text{BIAS} = 4.5 \text{ V to } 5.5 \text{ V}, I_{O}(DC) = 0$					20			20	μΑ
Va	A port	$V_{CC} = 0$	$V_{CC}BIAS = 4.5 V \text{ to } 5.$	5 V	1.1	1.5	1.9	1.1	1.5	1.9	V
Vo	Apon	vCC = 0	$V_{CC}BIAS = 4.75 V to 5$	BIAS = 4.75 V to 5.25 V		1.5	1.7	1.3	1.5	1.7	v
	A port		V _{CC} BIAS = 4.5 V	$V_{O} = 0$	-20		-100	-20		-100	μA
10	A port	$V_{CC} = 0,$	V (() () () () () () () () () () () () ()	V _O = 3 V	20		100	20		100	μA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $V_{\rm CC} = 0.5 \, \text{V} < V_{\rm CC} BIAS$

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(T	V _{CC} = 5 V, T _A = 25°C			SN54ABTE16245		SN74ABTE16245	
		(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	В	1.5	3.3	4.2	1.5	5.4	1.5	5.2	20
^t PHL	A	D	1.5	3.8	4.6	1.5	5.4	1.5	5.2	ns
^t PLH	В	٨	1.5	3	3.8	1.5	4.7	1.5	4.5	ns
^t PHL	в	А	1.5	3.1	4	1.5	4.7	1.5	4.5	115
^t PZH	ŌĒ	A	2	3.9	5.3	2	6.4	2	6.2	ns
^t PZL	ÛE		2	4.4	5.9	2	7	2	6.8	115
^t PZH	ŌĒ	P	2	4.5	6	2	7.3	2	7.1	20
^t PZL	OE	В	2	5	6.4	2	7.5	2	7.3	ns
^t PHZ	ŌĒ	٨	2	4.9	5.9	2	7	2	6.7	20
^t PLZ	UE	A	2	3.7	4.6	2	5.4	2	5.1	ns
^t PHZ	ŌĒ	В	2	5.2	6.2	2	7.2	2	7	20
^t PLZ	UE	D	2	4	5	2	5.8	2	5.5	ns



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extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD		CC = 5 V A = 25°C		SN54ABTE16245		SN74ABT	E16245	UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	В	А	Rχ = 13 Ω	1.5	3.2	4	1.5	5	1.5	4.8	ns
^t PHL	d	~	$K\chi = 13.22$	1.5	3.8	4.7	1.5	5.8	1.5	5.6	115
^t PLH	В	А	$\mathbf{P}_{\mathbf{V}} = 26 \mathbf{O}$	1.5	3.1	4	1.5	4.8	1.5	4.6	ns
^t PHL	D	A	Rχ = 26 Ω	1.5	3.5	4.4	1.5	5.2	1.5	4.9	115
^t PLH	В	А		1.5	3	3.8	1.5	4.7	1.5	4.5	
^t PHL	В	A	Rχ = 56 Ω	1.5	3.3	4.2	1.5	5.1	1.5	4.7	ns
	В	А	Rχ = Open		0.1	0.6		2		2	
^t sk(p)	А	В	Rχ = Open		0.4	0.8		2		2	ns
	В	А	Rχ = 26 Ω		0.3	0.8		2		2	
	В	A	Rχ = Open		0.3	0.7		1.3		1.3	
^t sk(o)	А	В	Rχ = Open		0.7	1.1		1.3		1.3	ns
	В	А	$R_X = 26 \Omega$		0.5	1		1.3		1.3	
tt‡	В	А	Rχ = 26 Ω	0.5	0.8	1.5	0.5	1.5	0.5	1.5	ns
tt‡	А	В	Rχ = Open	3.5	5.5	7.3	3.5	8.1	3.5	7.9	ns

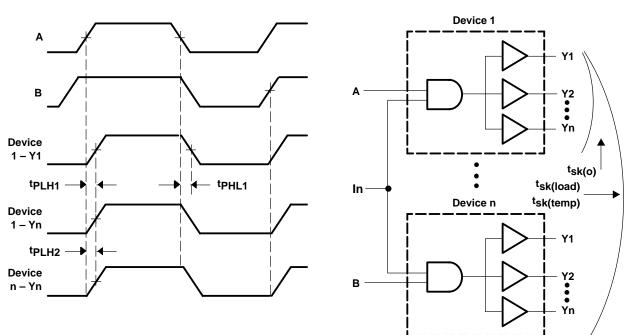
[†] t_t is measured between 1 V and 2 V of the output waveform. [‡] t_t is measured between 10% and 90% of the output waveform.

extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (see Figures 1 and 2)

DADAMETED	FROM	то	TEST CONDITIONS	LOAD	SN54ABTE	16245	SN74ABTE	16245	UNIT	
PARAMETER	PARAMETER (INPUT) (OUTPUT				MIN	MAX	MIN	MAX	UNIT	
• • • • •	А	В	V _{CC} = constant,			3		2.5		
^t sk(temp)	В	А	$\Delta T_A = 20^{\circ}C$	Rχ = 56 Ω		4.5		4	ns	
^t sk(load)	В	В	V _{CC} = constant, Temperature = constant	Rχ = 13, 26, or 56 Ω		4.5		4	ns	



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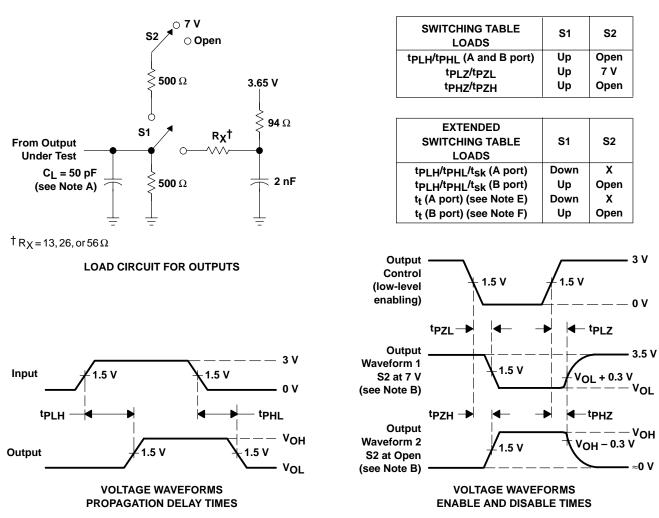
PARAMETER MEASUREMENT INFORMATION

- NOTES: A. Pulse skew, t_{sk(p)}, is defined as the difference in propagation-delay times t_{PLH1} and t_{PHL1} on the same terminal at identical operating conditions.
 - B. Output skew, t_{sk(0)}, is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g., |t_{PLH1} t_{PLH2}|).
 - C. Temperature skew, $t_{sk(temp)}$, is the output skew of two devices, both having the same value of $V_{CC} \pm 1\%$ and with package temperature differences of 20°C.
 - D. Load skew, $t_{sk(load)}$, is measured with R_X in Figure 2 at 13 Ω for one unit and 56 Ω for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tt is measured between 1 V and 2 V of the output waveform.
- F. t_t is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9677501QXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type
74ABTE16245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTE16245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABTE16245WD	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK

WD (R-GDFP-F**)

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only
 - E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 - GDFP1-F56 and JEDEC MO-146AB



MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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